MC10EP89

3.3V / 5V ECL Coaxial Cable Driver

ON Semiconductor®

http://onsemi.com

Description

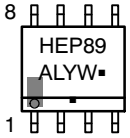
The MC10EP89 is a differential fanout gate specifically designed to drive coaxial cables. The device is especially useful in digital video broadcasting applications; for this application, since the system is polarity free, each output can be used as an independent driver. The driver produces swings 70% larger than a standard ECL output. When driving a coaxial cable, proper termination is required at both ends of the line to minimize signal loss. The 1.6 V (5 V) and 1.4 V (3.3 V) swing allow for termination at both ends of the cable, while maintaining a 800 mV (5 V) and 700 mV (3.3 V) swing at the receiving end of the cable. Because of the larger output swings, the device cannot be terminated into the standard V_{CC}−2.0 V. All of the DC parameters are tested with a 50 Ω to V_{CC}−3.0 V load. The driver accepts a standard differential ECL input and can run off of the digital video broadcast standard −5.0 V supply.

Features

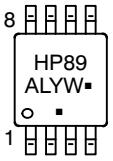
- 310 ps Typical Propagation Delay
- Maximum Frequency > 2 GHz Typical
- 1.6 V (5 V) and 1.4 V (3.3 V) V_{OUTpp} Swing
- PECL Mode Operating Range: V_{CC} = 3.0 V to 5.5 V with V_{EE} = 0 V
- NECL Mode Operating Range: V_{CC} = 0 V with V_{EE} = −3.0 V to −5.5 V
- Open Input Default State
- Safety Clamp on Inputs
- Q Output Will Default LOW with Inputs Open or at V_{EE}
- Pb−Free Packages are Available

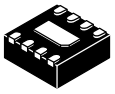
MARKING DIAGRAMS*

SOIC−8
D SUFFIX
CASE 751

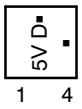


TSSOP−8
DT SUFFIX
CASE 948R





DFN8
MN SUFFIX
CASE 506AA



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
D = Date Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

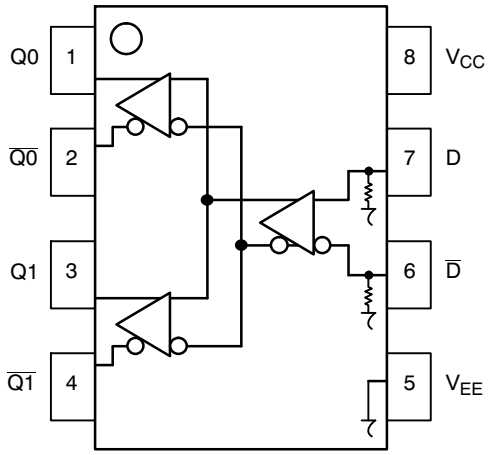


Figure 1. 8−Lead Pinout (Top View) **and Logic Diagram**

Table 1. PIN DESCRIPTION

PIN	FUNCTION
D*, $\overline{D}$*	ECL Data Inputs
Q0, Q1, $\overline{Q0}$, $\overline{Q1}$	ECL Data Outputs
V_{CC}	Positive Supply
V_{EE}	Negative Supply

* Pins will default LOW when left open.

Table 2. ATTRIBUTES

Characteristics		Value	
Internal Input Pulldown Resistor		75 kΩ	
Internal Input Pullup Resistor		N/A	
ESD Protection	Human Body Model Machine Model Charged Device Model	> 4 kV > 200 V > 2 kV	
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)		Pb Pkg	Pb−Free Pkg
	SOIC−8 TSSOP−8 DFN8	Level 1 Level 1 Level 1	Level 1 Level 3 Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL−94 V−0 @ 0.125 in	
Transistor Count		152 Devices	
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test			

1. For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	V_{EE} = 0 V		6	V
V_{EE}	NECL Mode Power Supply	V_{CC} = 0 V		−6	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	V_{EE} = 0 V V_{CC} = 0 V	$V_I \leq V_{CC}$ $V_I \geq V_{EE}$	6 −6	V V
I_{out}	Output Current	Continuous Surge		50 100	mA mA
T_A	Operating Temperature Range			−40 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	8 SOIC 8 SOIC	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	8 SOIC	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	8 TSSOP 8 TSSOP	185 140	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	8 TSSOP	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T_{sol}	Wave Solder Pb Pb−Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 4. DC CHARACTERISTICS, PECL V_{CC} = 3.3 V, V_{EE} = 0 V (Note 2)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	24	30	36	26	34	40	30	36	42	mA
V_{OH}	Output HIGH Voltage (Note 3)	2130	2255	2405	2180	2336	2455	2200	2400	2475	mV
V_{OL}	Output LOW Voltage (Note 3)	500	784	1100	480	786	1100	440	882	1060	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	2070		2410	2170		2490	2240		2580	mV
V_{IL}	Input LOW Voltage (Single−Ended)	1350		1800	1350		1820	1350		1855	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 4)	2.0		3.3	2.0		3.3	2.0		3.3	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

2. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.3 V to −0.3 V.
3. All loading with 50 Ω to V_{CC} − 3.0 V.
4. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 5. DC CHARACTERISTICS, PECL V_{CC} = 5.0 V, V_{EE} = 0 V (Note 5)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	27	34	41	30	37	44	33	40	47	mA
V_{OH}	Output HIGH Voltage (Note 6)	3830	3955	4105	3880	4037	4155	3900	4102	4175	mV
V_{OL}	Output LOW Voltage (Note 6)	1900	2205	2500	1850	2265	2450	1850	2177	2450	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	3770		4110	3870		4190	3940		4280	mV
V_{IL}	Input LOW Voltage (Single−Ended)	3050		3500	3050		3520	3050		3555	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 7)	2.0		5.0	2.0		5.0	2.0		5.0	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.5 V to −0.5 V.
6. All loading with 50 Ω to V_{CC} − 3.0 V.
7. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 6. DC CHARACTERISTICS, NECL V_{CC} = 0 V, V_{EE} = −3.3 V (Note 8)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
IEE	Power Supply Current	24	30	36	26	34	40	30	36	42	mA
V_{OH}	Output HIGH Voltage (Note 9)	−1170	−1145	−895	−1120	−964	−845	−1100	−900	−825	mV
V_{OL}	Output LOW Voltage (Note 9)	−2800	−2516	−2200	−2820	−2514	−2220	−2860	−2478	−2240	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	−1230		−890	−1130		−810	−1060		−720	mV
V_{IL}	Input LOW Voltage (Single−Ended)	−1950		−1500	−1950		−1480	−1950		−1445	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 10)	−1.3		0.0	−1.3		0.0	−1.3		0.0	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

8. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.3 V to −0.3 V.
9. All loading with 50 Ω to V_{CC} − 3.0 V.
10. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 7. DC CHARACTERISTICS, NECL V_{CC} = 0V, V_{EE} = −5.2 (Note 11)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
IEE	Power Supply Current	27	34	41	30	37	44	33	40	47	mA
V_{OH}	Output HIGH Voltage (Note 12)	−1170	−1045	−895	−1120	−964	−845	−1100	−900	−825	mV
V_{OL}	Output LOW Voltage (Note 12)	−3100	−2795	−2500	−3150	−2835	−2550	−3150	−2824	−2550	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	−1230		−890	−1130		−810	−1060		−720	mV
V_{IL}	Input LOW Voltage (Single−Ended)	−1950		−1500	−1950		−1480	−1950		−1445	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 13)	−3.2		0.0	−3.2		0.0	−3.2		0.0	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

11. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.7 V to −0.3 V.
12. All loading with 50 Ω to V_{CC} − 3.0 V.
13. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 8. AC CHARACTERISTICS V_{CC} = 0V; V_{EE} = −3.0 V to −5.5 V or V_{CC} = 3.0 V to 5.5 V; V_{EE} = 0 V (Note 14)

		−40°C			25°C			85°C			
Symbol	**Characteristic**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Unit**
f_{max}	Maximum Toggle (See Figure 2 F_{max}/JITTER)		> 2			> 2			> 2		GHz
t_{PLH}, t_{PHL}	Propagation Delay to Output Differential	220	280	340	250	310	370	270	330	390	ps
t_{SKEW}	Within Device Skew Q, $\overline{Q}$ Device to Device Skew (Note 15)		5.0	20 120		5.0	20 120		5.0	20 120	ps
t_{JITTER}	Cycle−to−Cycle Jitter (See Figure 2 F_{max}/JITTER)		.5	< 1		.5	< 1		.5	< 1	ps
V_{PP}	Input Voltage Swing (Differential Configuration)	150	800	1200	150	800	1200	150	800	1200	mV
t_r t_f	Output Rise/Fall Times Q, $\overline{Q}$ (20% − 80%)	175	250	325	200	275	350	225	295	375	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

14. Measured using a 750 mV source, 50% duty cycle clock source. All loading with 50 Ω to V_{CC}−3.0 V.
15. Skew is measured between outputs under identical transitions.

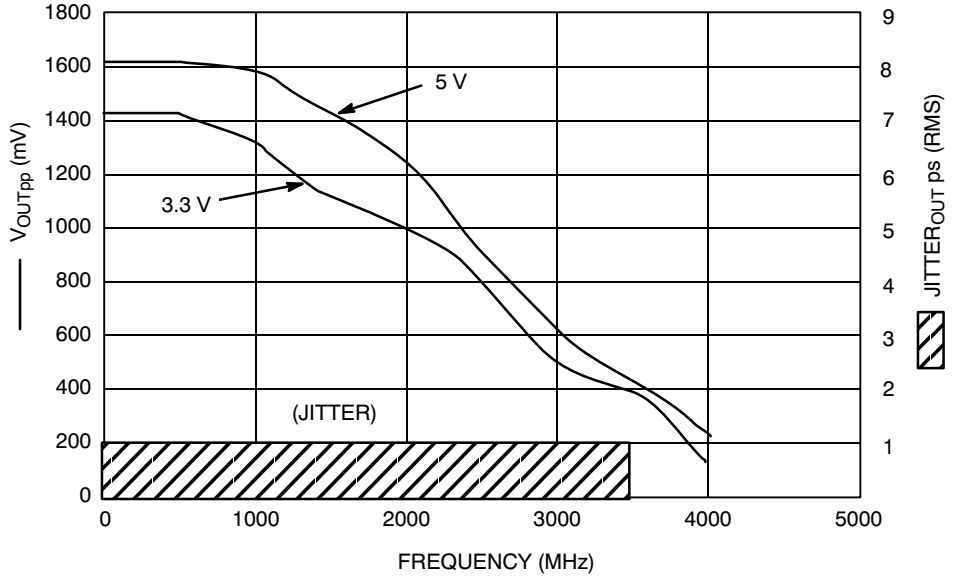


Figure 2. F_{max}/Jitter

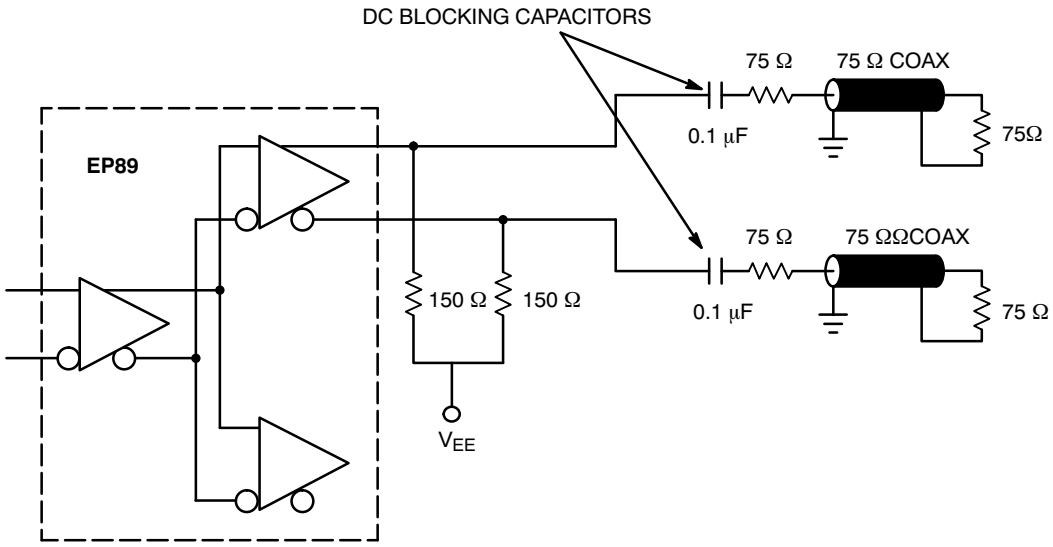


Figure 3. Cable Driver Termination Configuration

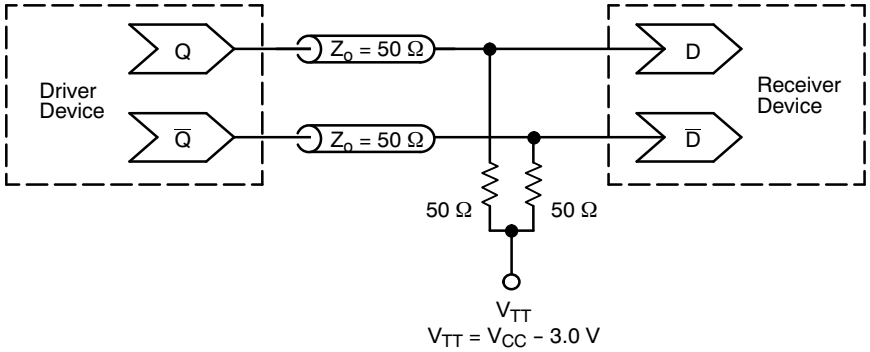


Figure 4. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping†
MC10EP89D	SOIC−8	98 Units / Rail
MC10EP89DG	SOIC−8 (Pb−Free)	98 Units / Rail
MC10EP89DR2	SOIC−8	2500 / Tape & Reel
MC10EP89DR2G	SOIC−8 (Pb−Free)	2500 / Tape & Reel
MC10EP89DT	TSSOP−8	100 Units / Rail
MC10EP89DTG	TSSOP−8 (Pb−Free)	100 Units / Rail
MC10EP89DTR2	TSSOP−8	2500 / Tape & Reel
MC10EP89DTR2G	TSSOP−8 (Pb−Free)	2500 / Tape & Reel
MC10EP89MNR4	DFN8	1000 / Tape & Reel
MC10EP89MNR4G	DFN8 (Pb−Free)	1000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D − ECL Clock Distribution Techniques

AN1406/D − Designing with PECL (ECL at +5.0 V)

AN1503/D − ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D − Metastability and the ECLinPS Family

AN1568/D − Interfacing Between LVDS and ECL

AN1642/D − The ECL Translator Guide

AND8001/D − Odd Number Counters Design

AND8002/D − Marking and Date Codes

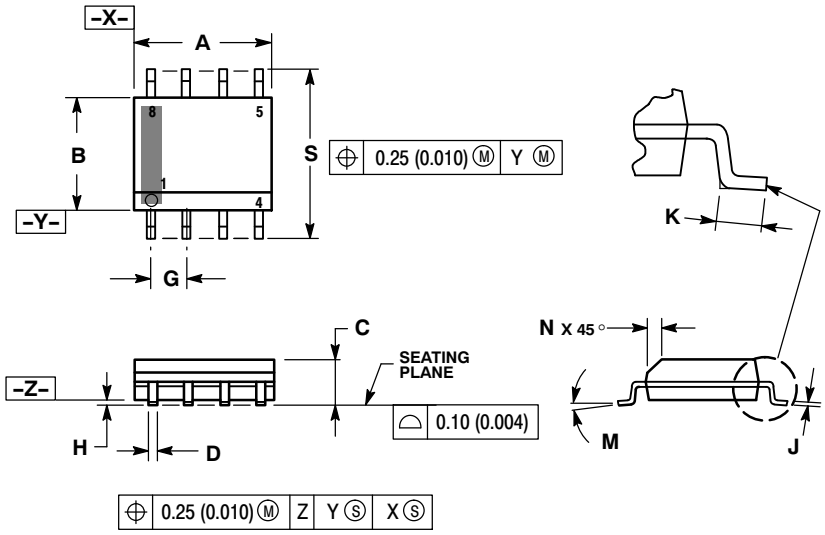
AND8020/D − Termination of ECL Logic Devices

AND8066/D − Interfacing with ECLinPS

AND8090/D − AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

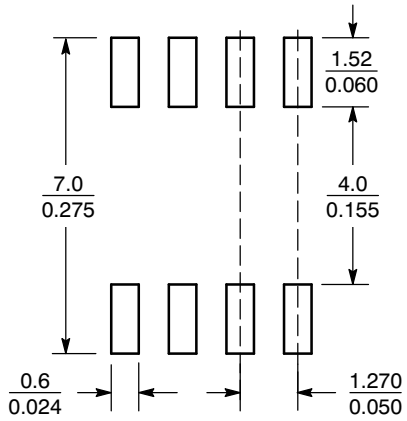
SOIC−8 NB
CASE 751−07
ISSUE AJ



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751−01 THRU 751−06 ARE OBSOLETE. NEW STANDARD IS 751−07.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*

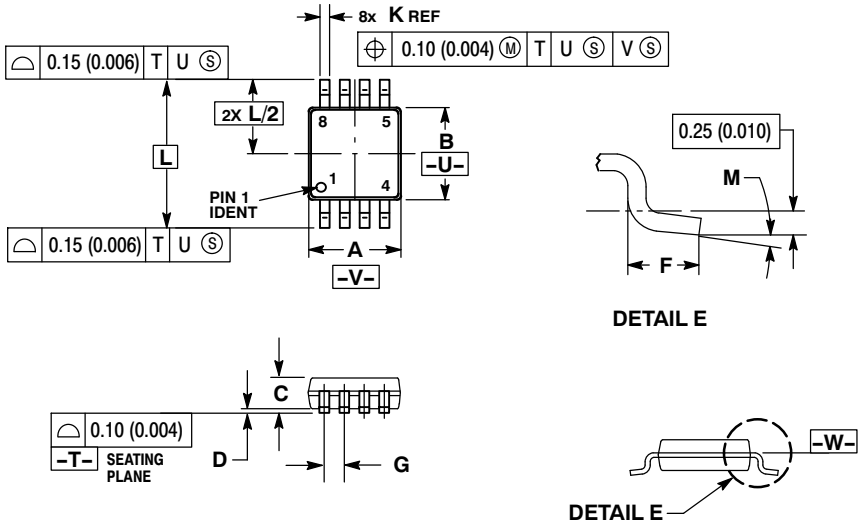


SCALE 6:1 (mm / inches)

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP−8
DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948R−02
ISSUE A

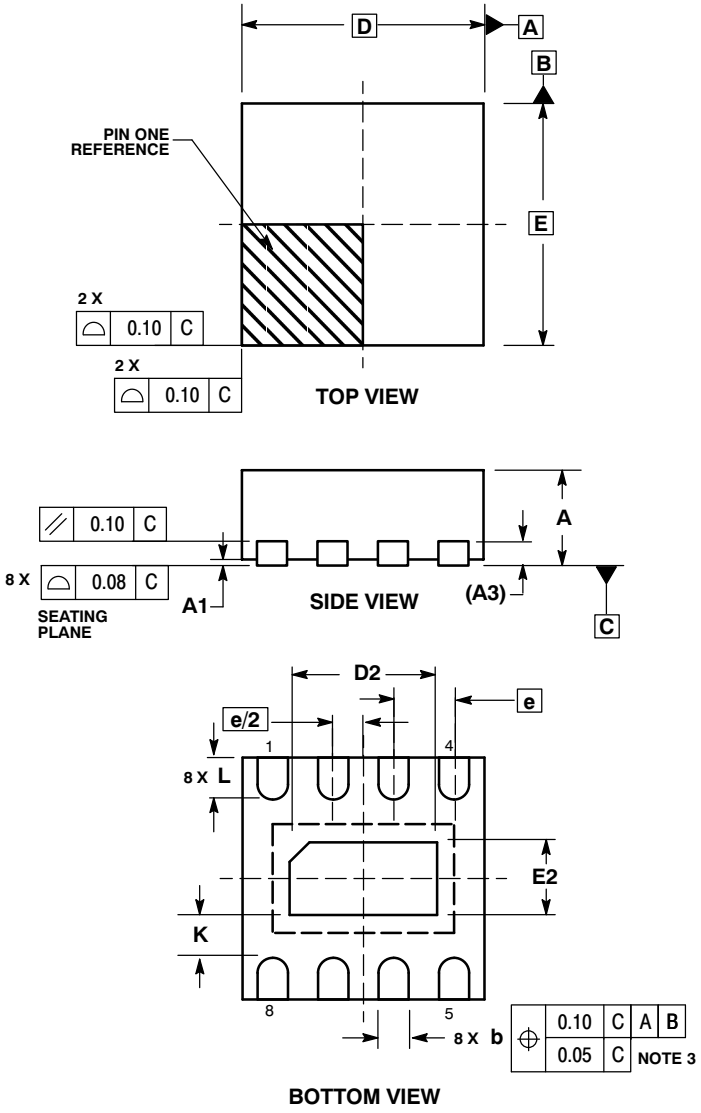


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6°	0°	6°

PACKAGE DIMENSIONS

DFN8
CASE 506AA−01
ISSUE D



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 .
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	2.00 BSC	
D2	1.10	1.30
E	2.00 BSC	
E2	0.70	0.90
e	0.50 BSC	
K	0.20	−−−
L	0.25	0.35

ECLinPS is a trademark of Semiconductor Components Industries, LLC (SCILLC).

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
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ON Semiconductor:

MC10EP89DG MC10EP89DR2G MC10EP89DTG MC10EP89DTR2G MC10EP89MNR4G